

**Cryogenic Si detectors  
for Ultra  
Radiation Hardness in SLHC Environment**

**Zheng Li (BNL)**

**On behalf of CERN RD39 Collaboration**

## Outline

- o Trapping effect on Charge Collection Efficiency (CCE) in SLHC

LHe temperature TCT setup

Operation of current-injected-detectors (CID)

CCE measurements on CID

Summary

## Trapping effect on CCE in S-LHC

$$CCE = CCE_{GF} \cdot CCE_t = \frac{w}{d} \cdot e^{-t_{dr}/\tau_t}$$

Trapping term

Depletion term

$CCE_{GF}$  is a geometrical factor

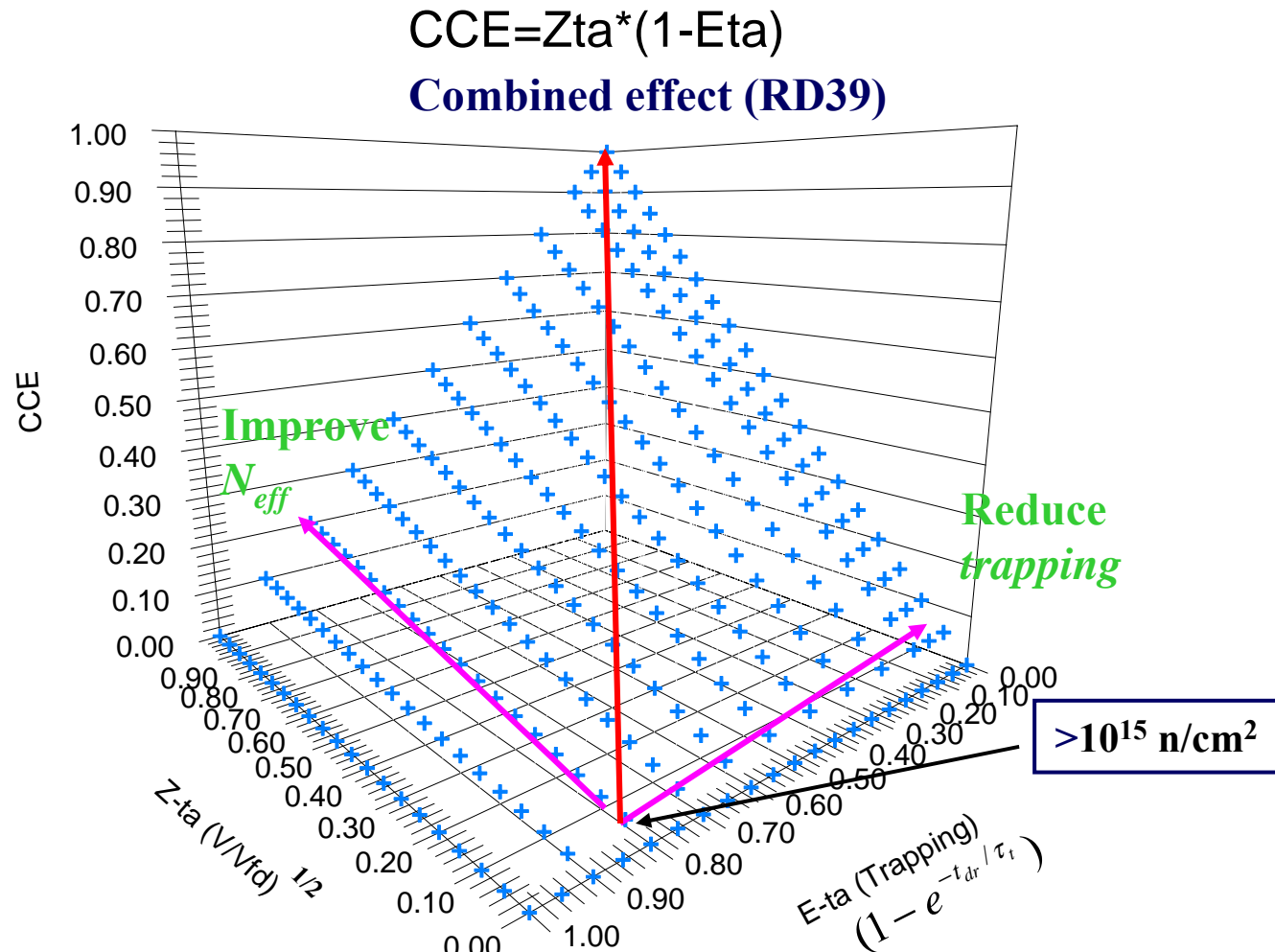
$$w = \sqrt{\frac{2\epsilon\epsilon_0 V}{eN_{eff}}} \quad \text{and} \quad \frac{w}{d} = \sqrt{\frac{V}{V_{fd}}}$$

$CCE_t$  is related with trapping

For fluence less than  $10^{15}$  n/cm<sup>2</sup>, the trapping term  $CCE_t$  is insignificant

For fluence  $10^{16}$  n/cm<sup>2</sup>, the trapping term  $CCE_t$  is a limiting factor of detector operation!

## To get better CCE:



Zheng Li on behalf of CERN RD39  
Collaboration, September 14, 2006

## TRAPPING

$$\tau_t = \frac{1}{\sigma v_{th} N_t}$$

The thermal velocity  $v_{th} \approx 10^7$  cm/s

$10^{16}$  cm<sup>-2</sup> irradiation produces  $N_T \approx 3-5 \cdot 10^{16}$  cm<sup>-3</sup> with  $\sigma \approx 10^{-14}$  cm<sup>2</sup>

On average (e and h) it gives a  $\tau_f \approx 0.2$  ns!

Even in highest E-field (Saturation velocity,  $10^7$  cm/s), carrier drifts only 20-30  $\mu$ m before it gets trapped regardless whether the detector is fully depleted or not !

In S-LHC conditions, about 90% of the volume of  $d=300\mu$ m detector is dead space !

- **Trapping time:  $\tau_t$**

- $1/\tau_t = \gamma \Phi_n$

- $\gamma_e = 7.50 \times 10^{-7} \text{ cm}^2/\text{s}$

H.W. Kraner et al., Nuclear Instruments and Methods in Physics Research  
A326 (1993) 350-356

- $\gamma_h = 3.75 \times 10^{-7} \text{ cm}^2/\text{s}$

- **for  $10^{16} \text{ n}_{\text{eq}}/\text{cm}^2$ :**

$$\tau_{te} = 0.13 \text{ ns}$$

$$\tau_{th} = 0.26 \text{ ns}$$

$\tau_t = 0.20 \text{ ns}$  as average

**Trapping distance (or effective charge collection distance) is:**

$d_{\text{eff}} \leq \tau_t \times V_s = 20 \text{ } \mu\text{m} \ll d$ , the detector thickness or depletion depth

**The main limiting factor is trapping for SLHC!**

# Effective CCE thickness

$d$ : thickness (200- 300  $\mu\text{m}$ )

$w$ : depletion depth ( $\leq d$ )

$t$ : trapping distance (20-50  $\mu\text{m}$ )

*Thickness  $d$*

$$Q(t) = Q(w) \cdot t/w$$

$$Q(w) = W/d \cdot Q_0$$

$$Q(t) = Q_0 \cdot t/d$$

*The same!*

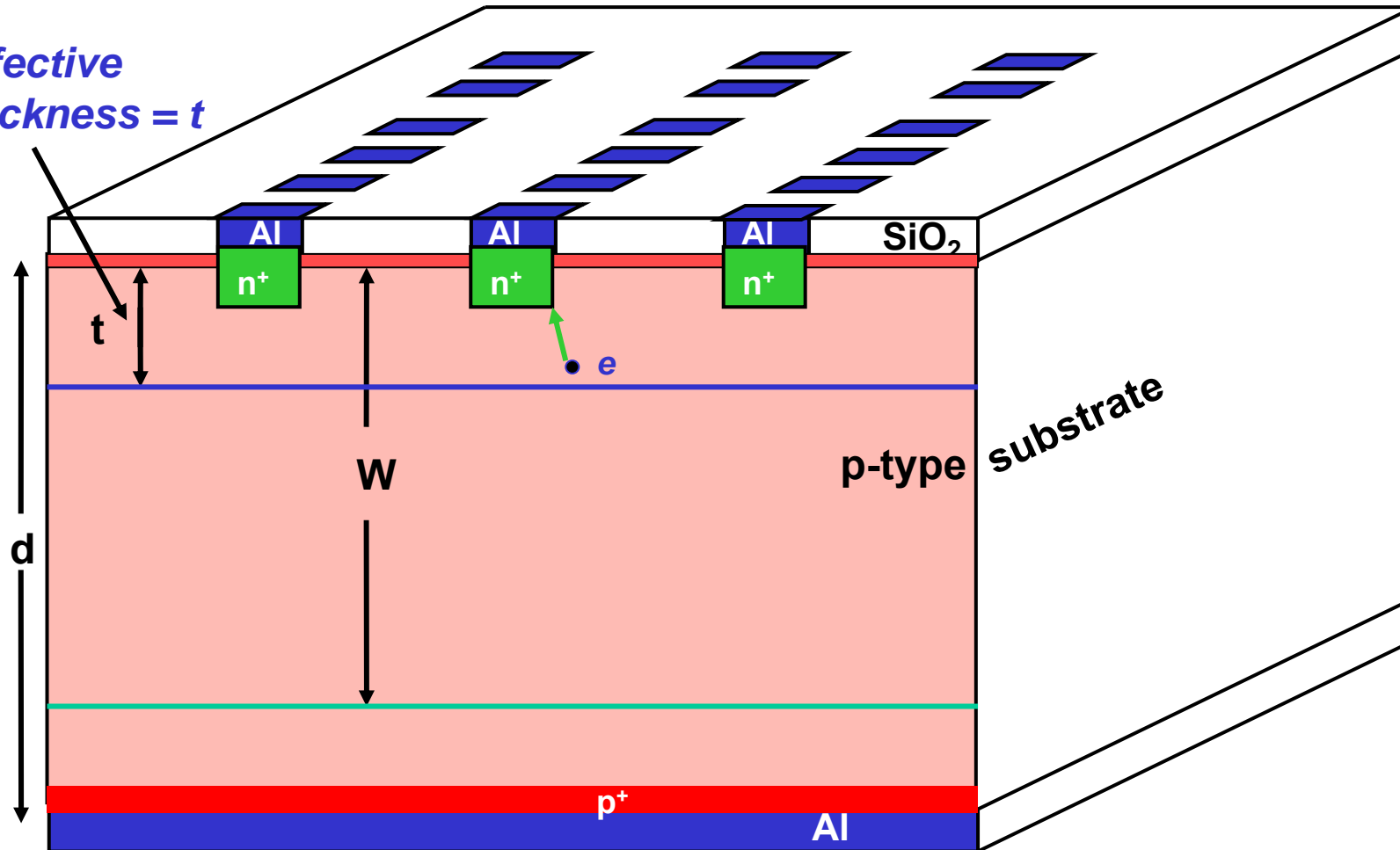
*Thickness  $t$  (fully depleted,  $t = w$ )*

$$Q(t) = Q(w) \cdot t/w = Q(w)$$

$$Q(w) = w/d \cdot Q_0 = t/d \cdot Q_0$$

$$Q(t) = Q_0 \cdot t/d$$

*Effective thickness =  $t$*



## Possible Si detector solutions for SLHC's most inner region

<b>Solution</b>	<b>CCE improvement due to</b>	<b>Technology/ implementation difficulties</b>
<b>Replacement every 1-2 years</b>	<b>New detectors</b>	<b>Hard to access the inner region</b>
<b>3D Si detectors</b>	<b>Small <math>V_{fd}</math> Small drift distance <math>t</math></b>	<b>Complicated processing technology Column spacing <math>t</math> should be <math>&lt; 40</math> <math>\mu\text{m}</math> Possible surface damage problem to ionizing radiation</b>
<b>Cryogenic Si detectors</b>	<b>Fixed electric field (small bias) Freezing traps (low trapping) Low leakage current</b>	<b>Difficult to implement cryogenic system</b>
<b>Elevated temp annealing (DRIVE) (MCZ Si only, <math>\geq 400</math> °C)</b>	<b>Annealing out of defect levels related to: Leakage current, space charges And trapping</b>	<b>Difficult to implement annealing in a full detector system</b>



# DETRAPPING

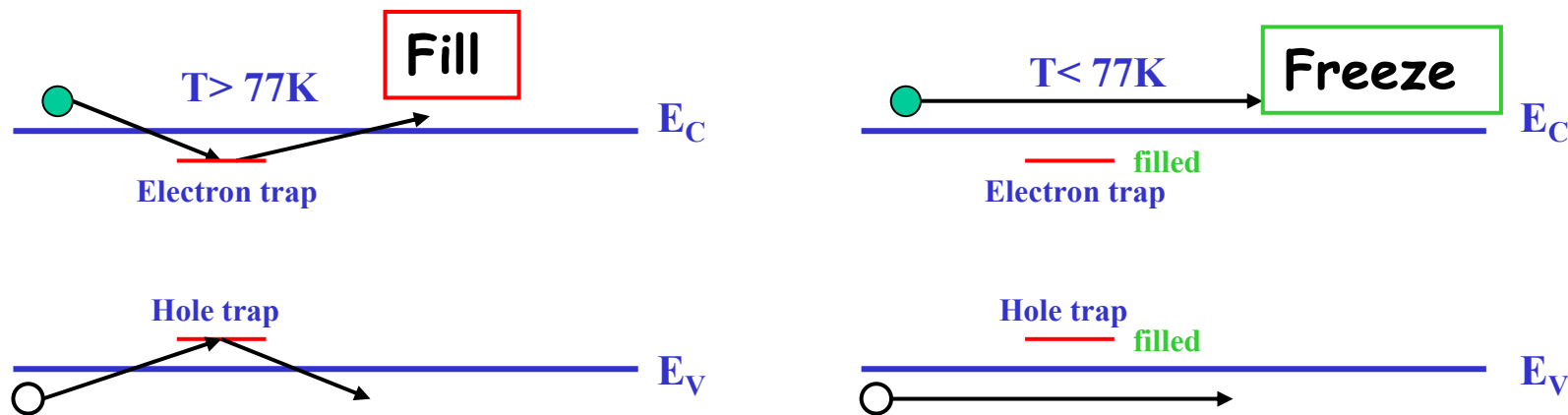
$$\tau_d = \frac{1}{\sigma v_{th} N_C e^{-E_t/kT}}$$

If a trap is filled (electrically non-active) the detrapping time-constant is crucial

The detrapping time-constant depends exponentially on T

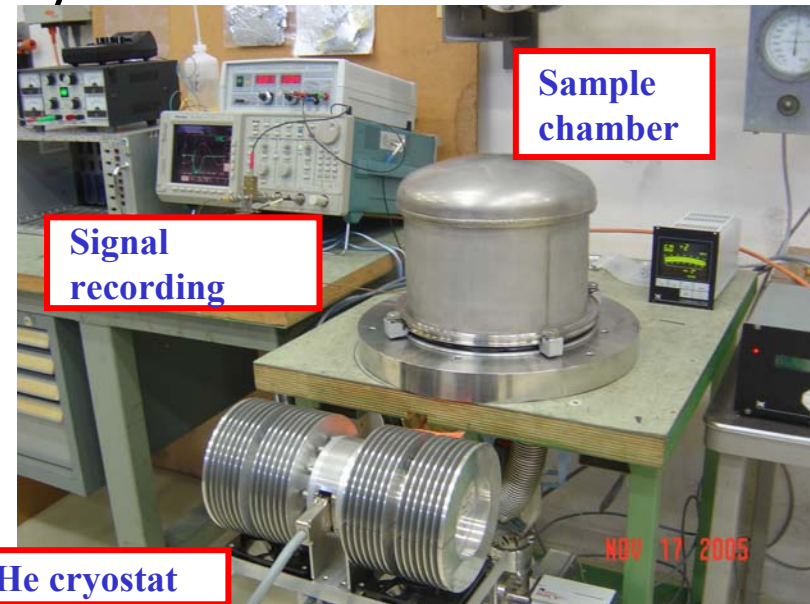
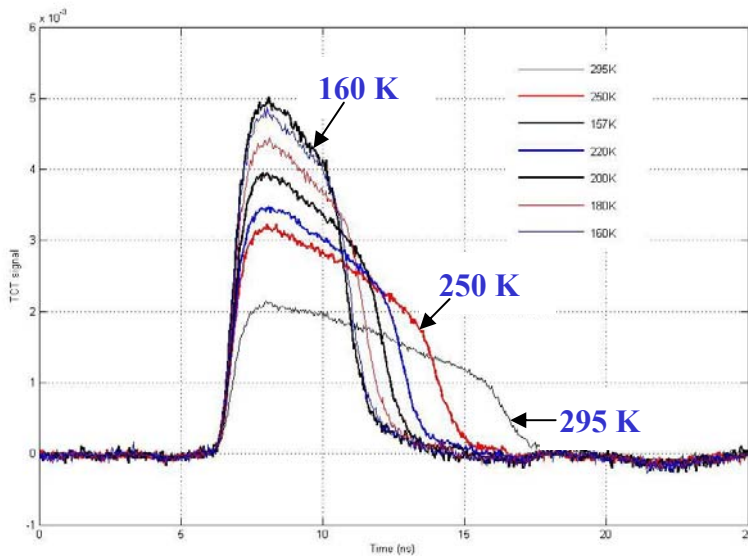
For A-center (O-V at  $E_c - 0.18$  eV with  $\sigma \approx 10^{-15}$  cm<sup>2</sup>)

<b>T(K)</b>	300	150	100	77	60	55	50	48	47	46
<b><math>\tau_d</math></b>	3.7 ns	3.9 $\mu$ s	4 ms	2 s	1.22 hrs	1.2 days	53 days	302 days	2.1 years	5.47 years



# LHe Temp TCT Setup

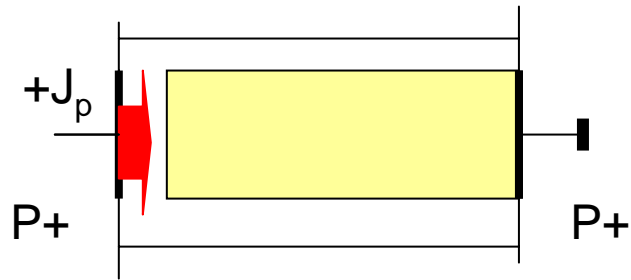
- A fast TCT setup at CERN with sub-LN<sub>2</sub> temp for CCE measurements
- All components of the setup have been made
- The electrical part (TCT with ps laser) and the He cryostat are now operational
- The final calibration and actual CCE measurements at sub-LN<sub>2</sub> temperatures are now underway



**First TCT signal of a Si detector** Zheng Li on behalf of CERN RD39 Collaboration, September 14, 2006

**He cryostat, to 40 K in 2 hours**

# Current injected detector (principle of operation)



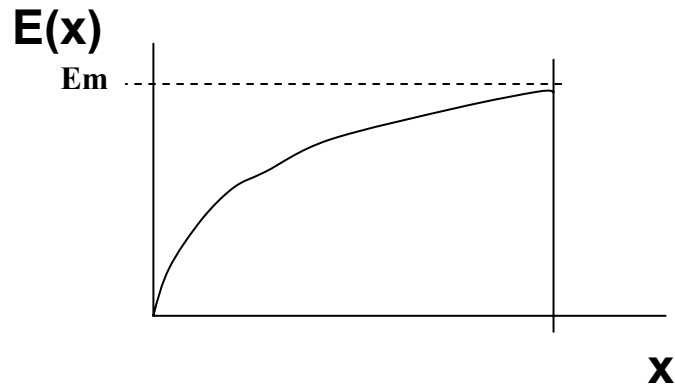
$$J_p = e p \mu E$$

$$\text{div} J = 0$$

$$\text{div} E = p_{tr}$$

$$E(x=0) = 0$$

(SCLC: Space Charge Limited Current mode)



$$E(x) = \frac{3V}{2d} \cdot \sqrt{\frac{x}{d}} \quad E_m = \frac{3}{2} \cdot \frac{V}{d}$$

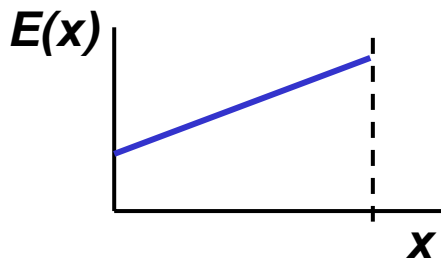
The key advantage:

The shape of  $E(x)$  is **not affected** by fluence

Zheng Li on behalf of CERN RD39

Collaboration, September 14, 2006 V. Eremin, RD39, CERN, November 11, 2005

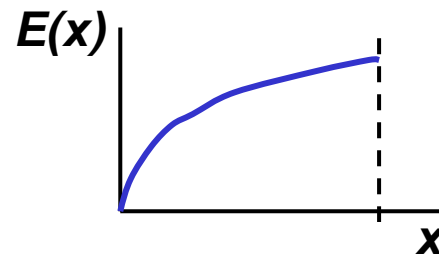
# Evolution of $E(x)$ in CID with the injected current



**“Diode” mode**

$$p > p_{tr}$$

$$E(x) \sim E(0) + ax$$

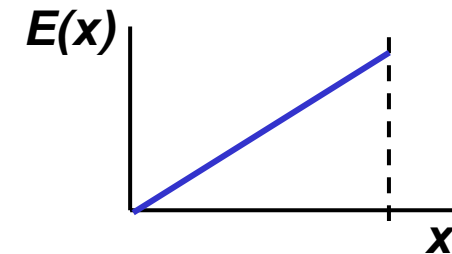


**SCLC mode**

$$N_{dl} > p_{tr}$$

$$E(x) \sim SQR(x)$$

$$J \sim V^2$$

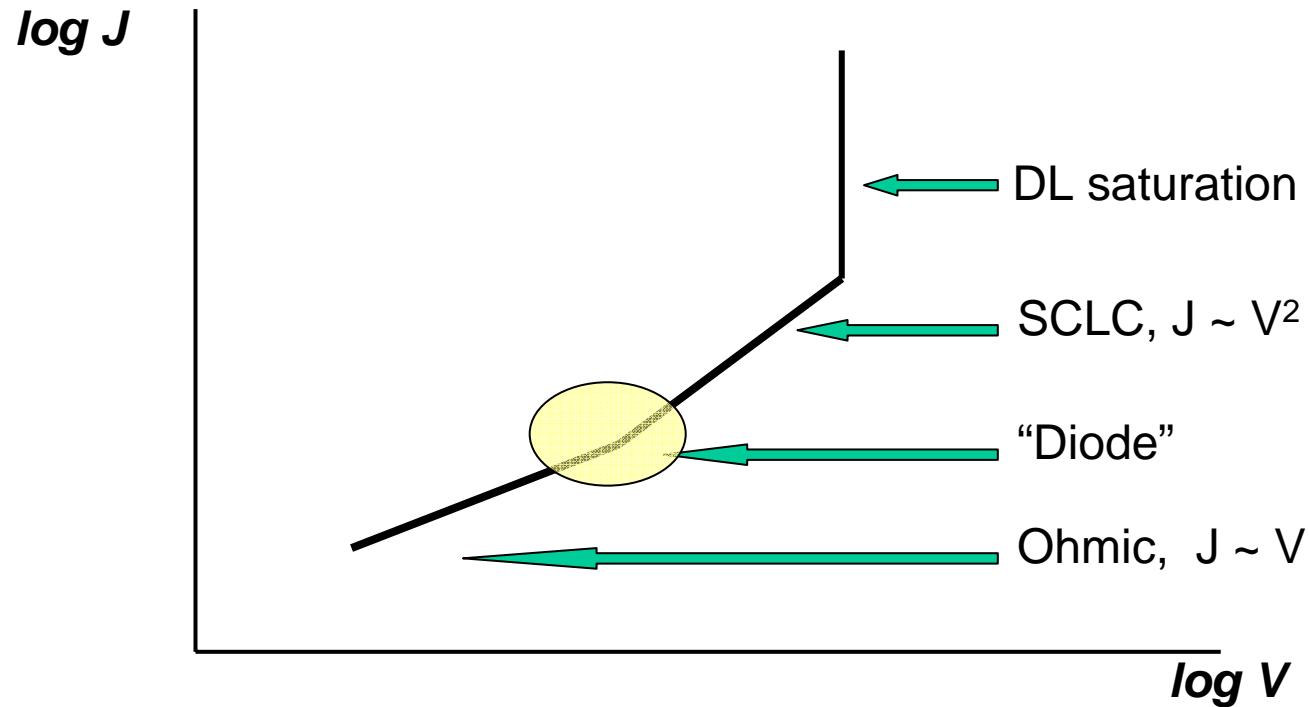


**Deep Level saturation**

$$p \gg p_{tr}$$

$$E(x) = ax$$

## *I-V characteristic of CID*



**Proof of CID concept: – *observation of SCLC and DL saturation behavior***

**Problem: - *optimal range of V for CID operation***

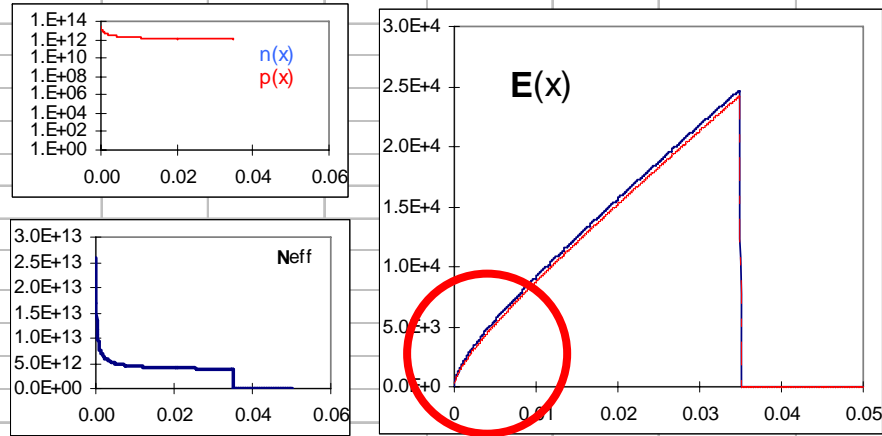
Zheng Li on behalf of CERN RD39  
Collaboration, September 14, 2006

# CID I-V simulation software

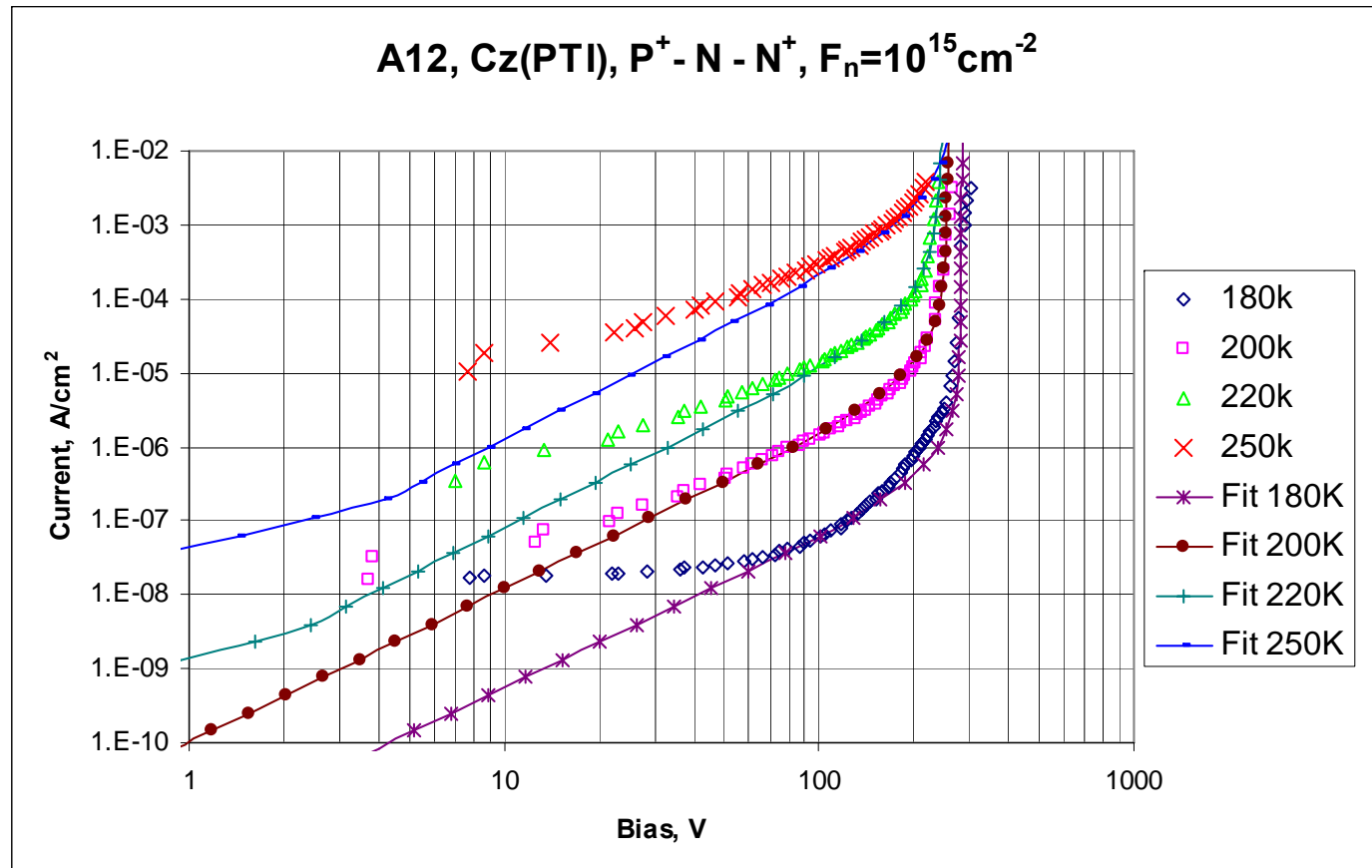
CID I-V simulation													
Sample parameters		Physical constants				Calculated values							
d [cm]	0.035	eps0 [F/m]	8.85E-14	mu [cm2/V*s]									
Uc [V]	0	eps	11.7	Vs									
NO [cm-3]	0.00E+00	q [C]	1.60E-19	Vth*Nc	4.13E+26								
Operation parameters		k [J/K]	1.38E-23	Vth*Nv	1.25E+26								
Ub [V]	30	μoe [cm^2/Vs]	2.08E+03	Nc [cm-3]	2.1741E+19								
Temperature	250	vse [cm/s]	1.12E+07	Nv [cm-3]	8.6963E+18								
dX [cm]	1.00E-04	be [T]	7.82E-01	ni [T], cm-3	7.23E+07								
Injected current		μoh [cm^2/Vs]	8.17E+02										
Egen, eV	0	vsh [cm/s]	8.14E+06	IntN(d)	0.00E+00								
Sig(e), cm2	0.00E+00	bh [T]	9.87E-01	Vth(e), cm/s	1.90E+07								
Sig(h), cm2	0.00E+00	Eg (eV)	1.12	Vth(h), cm/s	1.44E+07								
M, cm-3	0.00E+00	Parameter	Ef, eV	0.56									
Jn [A/cm2]	0.00E+00	Calculated	Ef, eV	0.01									
Jp [A/cm2]	1.00E+00												
MACRO													
<i>E(x) calculation</i>		<i>I-V calculation</i>											
Iterations	2	Imin, A/cm2	1.00E-12										
Kdesipaiton	0.8	points	50										
		Imax, A/cm2	1.00E+00										
<b>start</b>													
Row	X	E0(x)	E1(x)	n(x)	p(x)	Ff(x)	Neff(x)	Ff(x)	Neff(x)	Ff(x)	Neff(x)	Ff(x)	Neff(x)
#	cm	V/cm	v/cm	cm-3	cm-3								

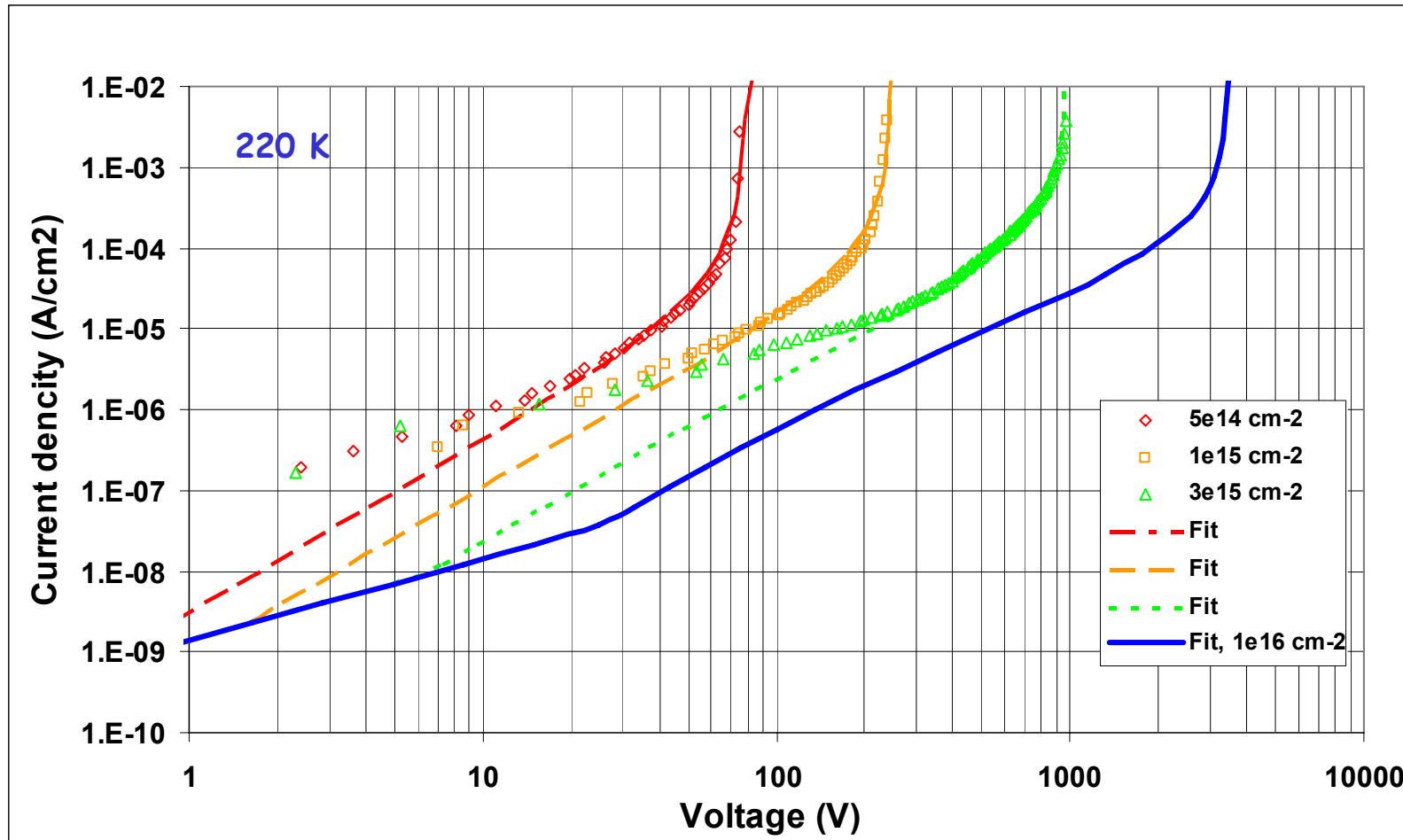
DL #	shallow donors		deep acceptor		deepdonor		shallow acceptors	
D/A, 0/1	0		1		0		1	
	electrons	holes	electrons	holes	electrons	holes	electrons	holes
Et=Edl-Ev	1.117		0.6		0.48	0.64	0.55	0.57
sig/e [cm2]	1.00E-15		1.00E-17		1.00E-15		5.00E-15	
sig/h [cm2]		1.00E-15		1.00E-15		1.00E-15		5.00E-15
Ndl [cm-3]	0.00E+00		0.00E+00		2.80E+12		0.00E+00	
Sig*vth	1.90E-08	1.44E-08	1.90E-10	1.44E-08	1.90E-08	1.44E-08	9.49E-08	7.19E-08
detrapp.prob.	3.59E+11	3.97E-12	1.39E-01	1.03E-01	5.31E-02	2.69E+01	6.82E+00	5.23E+00



# *I-V characteristics of CID*



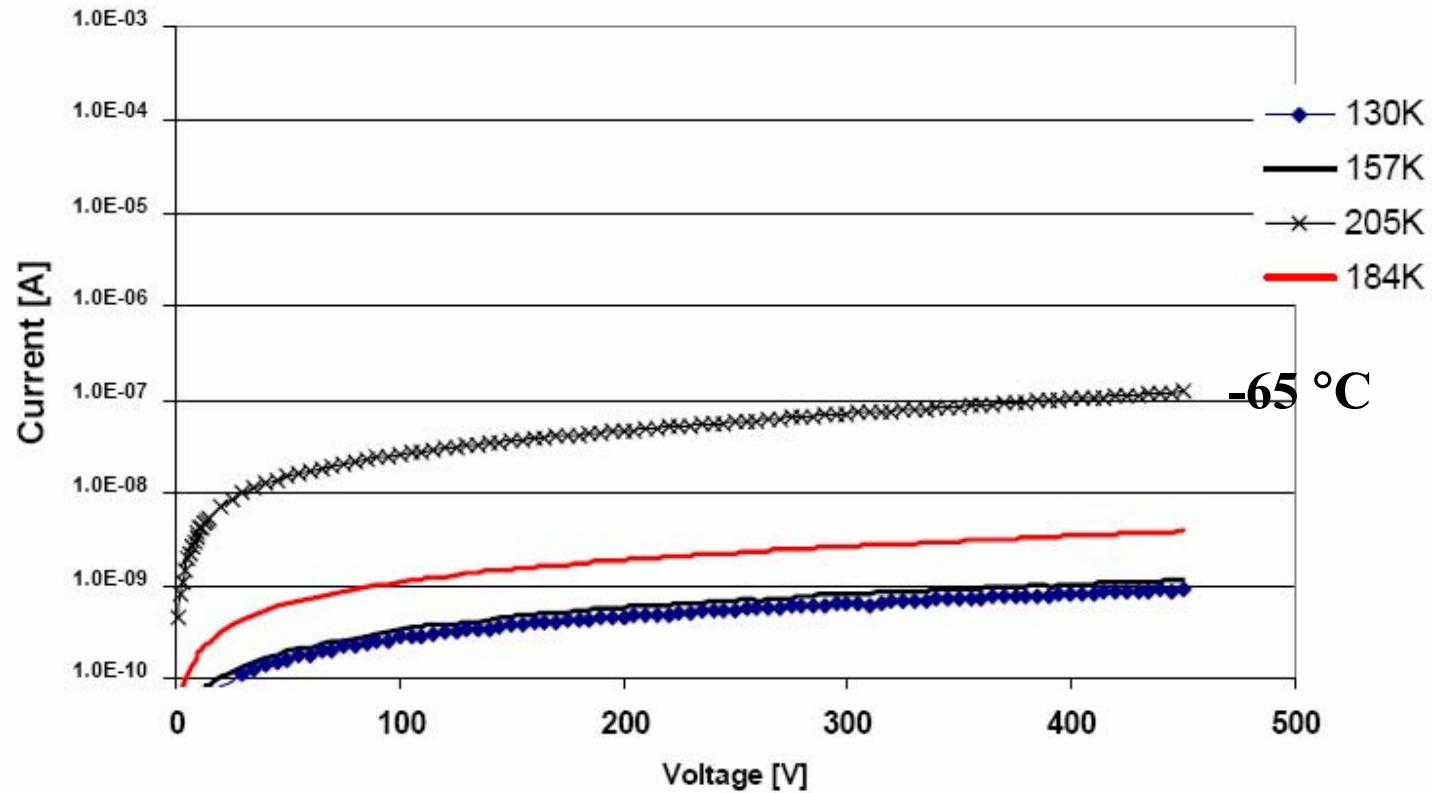
## *I-V characteristics of CID*



Zheng Li on behalf of CERN RD39  
Collaboration, September 14, 2006




# SLHC fluencec



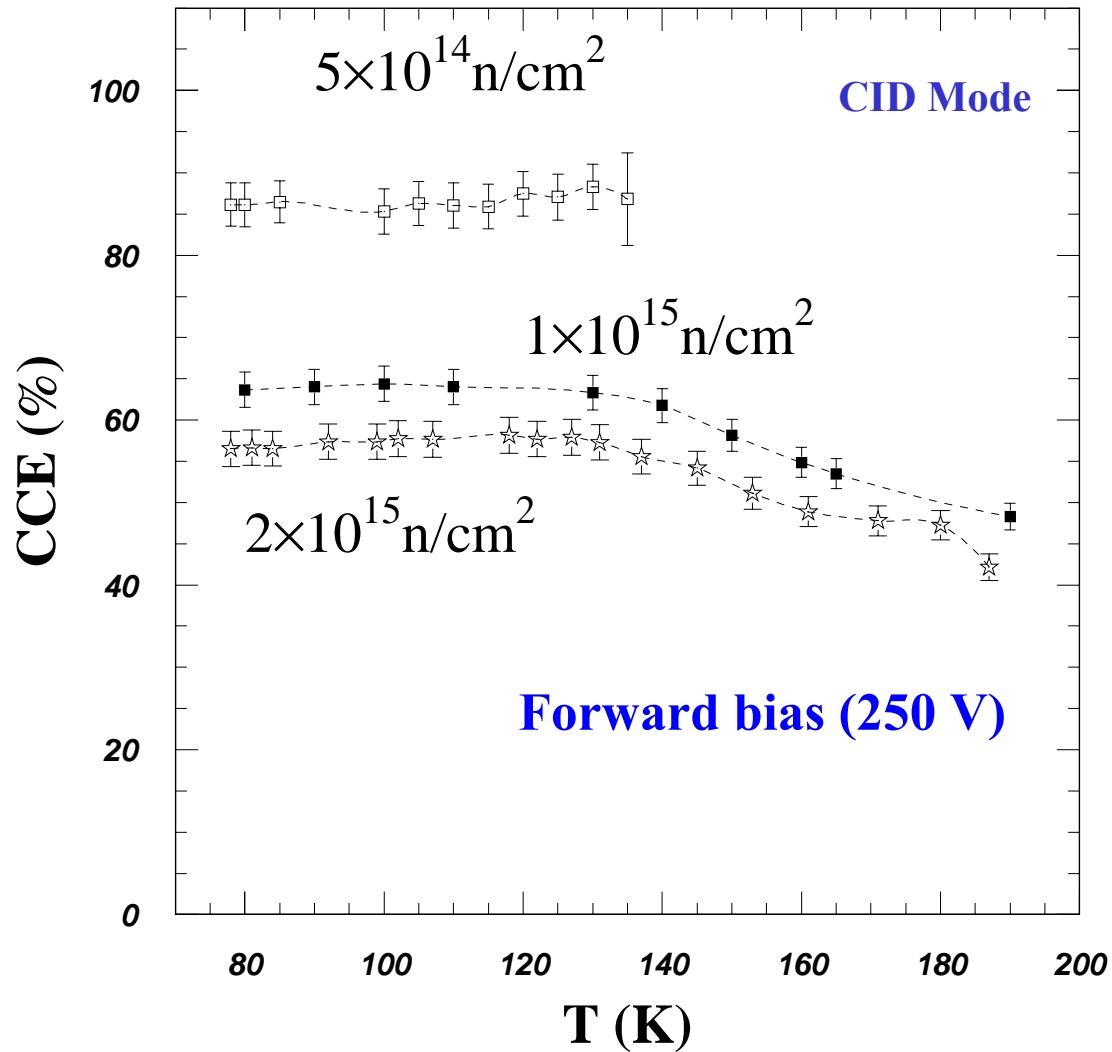
MCz-Si 9MeV proton irradiated  $7 \times 10^{15}$  1MeV  $n_{eq}/\text{cm}^2$

Zheng Li on behalf of CERN RD39  
Collaboration, September 14, 2006

## *Main advantages CID over standard PN detectors*

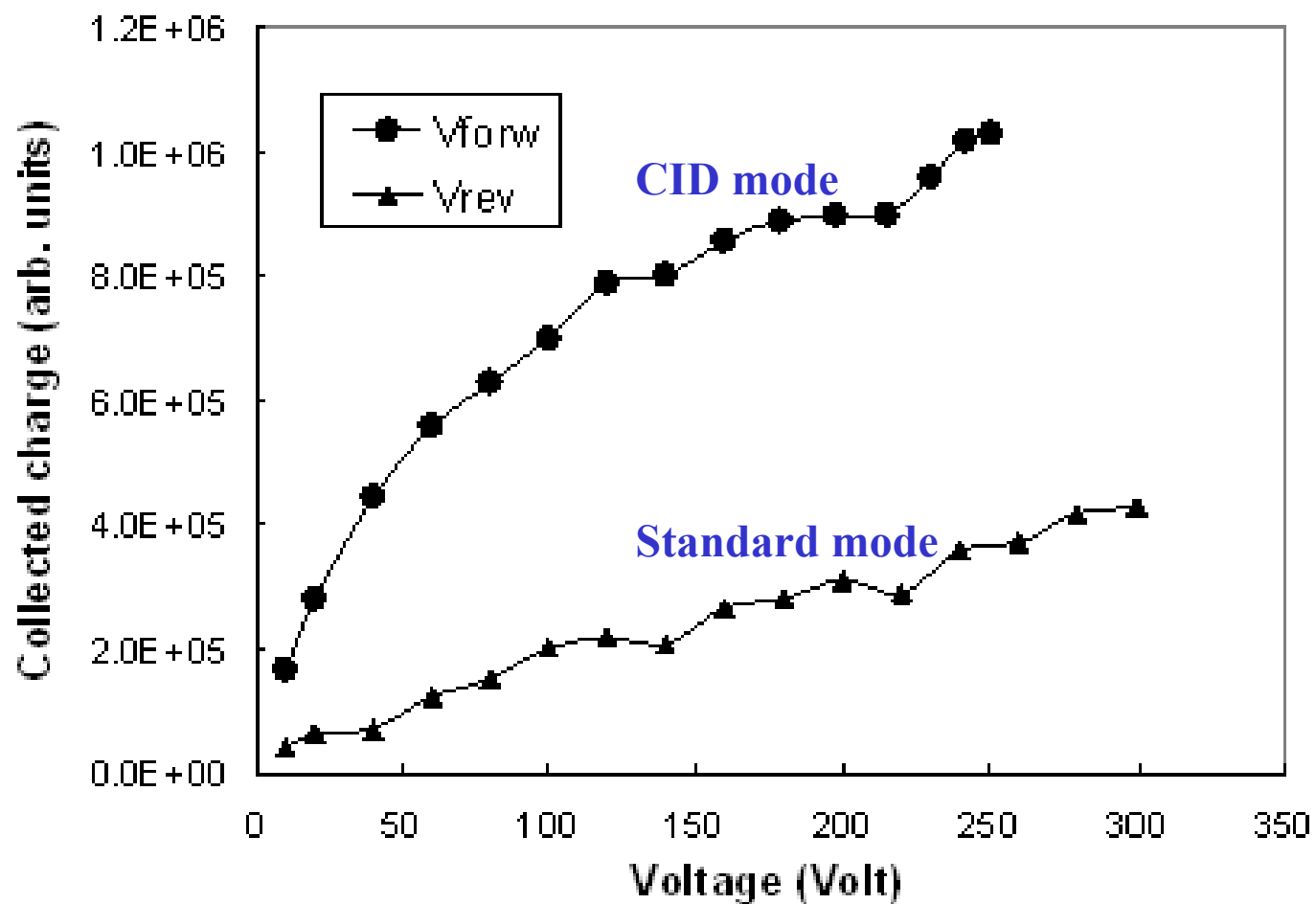
1. The detectors are always fully depleted
2. The electric field profile does not change with fluence
3. Much lower bias voltage is needed
4. The higher the radiation fluence, the lower the operation current at given bias and temperature
5. The operation bias range increases with fluence
6. No breakdown problem due to self-adjusted electric field by space charge limited current feedback effect
7. Simple detector processing technology (single-sided planar technology)
8. Injection can also be used to deactivate trapping centers --- CCE 

# CCE to $^{90}\text{Sr}$ source at various temperatures for CID



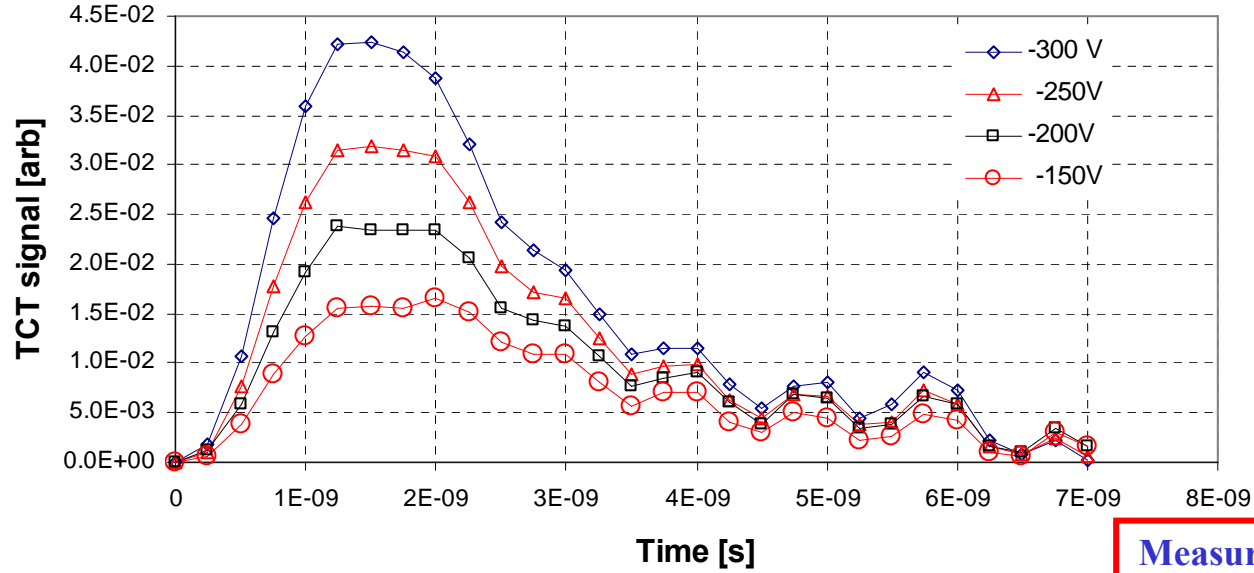
Zheng Li on behalf of CERN RD39  
Collaboration, September 14, 2006

$\Phi_n = 1 \times 10^{15} \text{ cm}^{-2}$ ,  $T = 180 \text{ K}$ , MIPs (1050 nm laser)

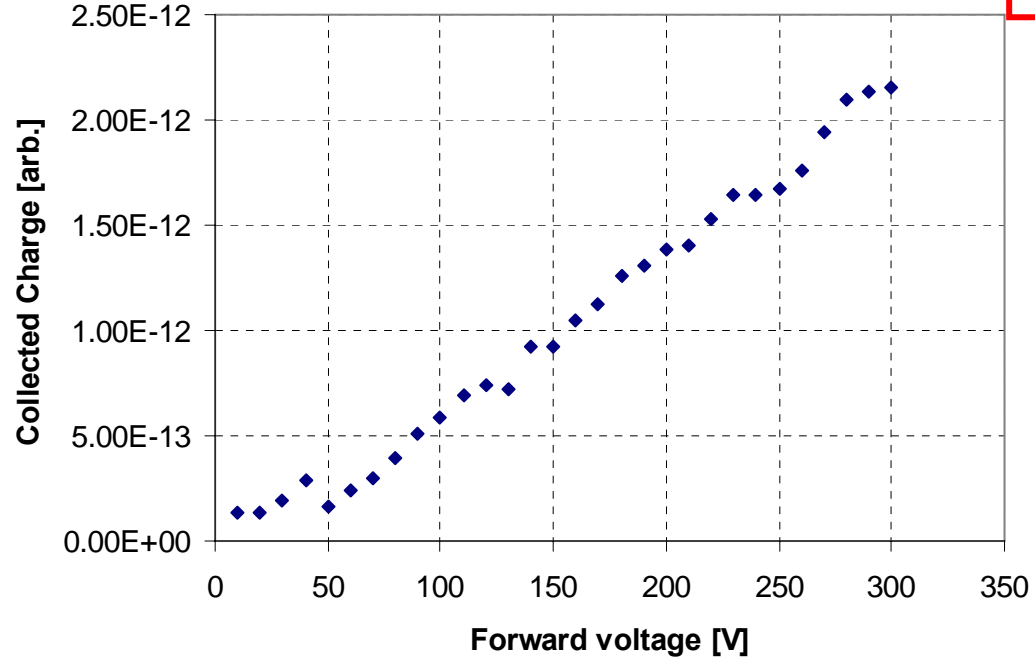


Zheng Li on behalf of CERN RD39  
Collaboration, September 14, 2006

# CID mode



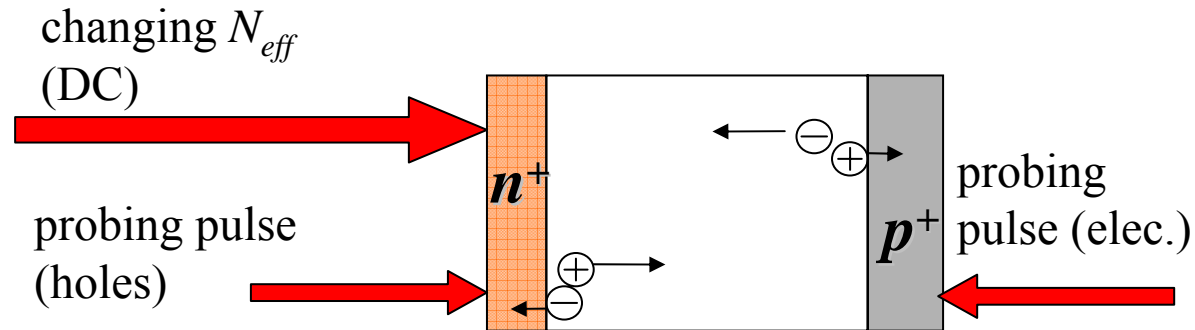
Measurements from He cryostat, at 60K



P-type MCZ, red laser  $1 \times 10^{15}/\text{cm}^2$

# Charge Injected Diode

high  $p$  : continuous (DC) illumination of  $n^+$  side by red laser:



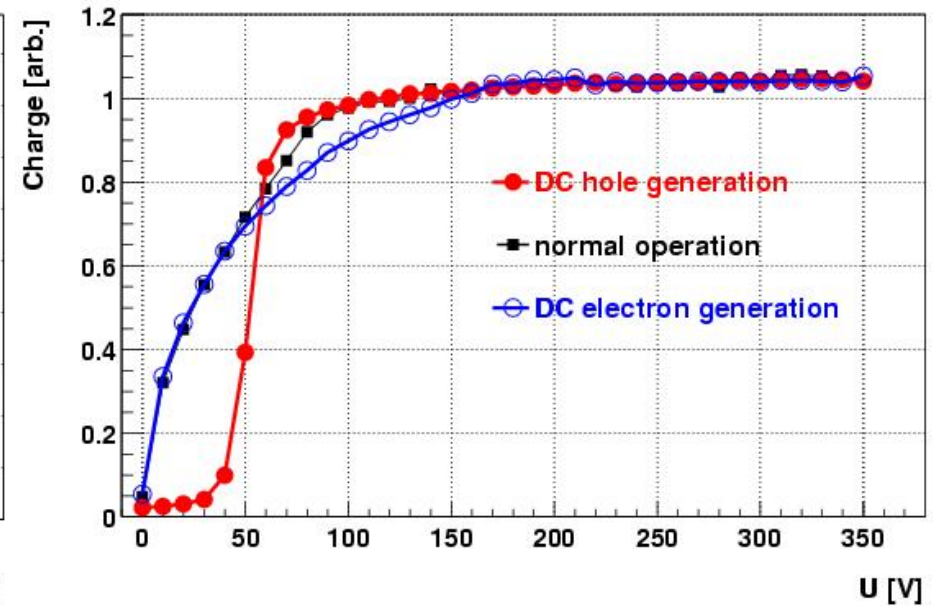
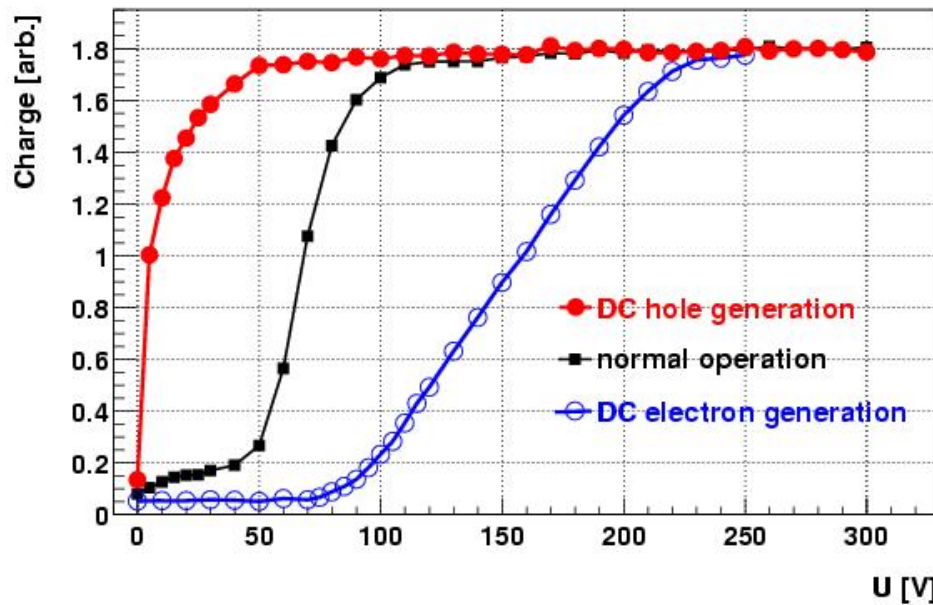
$$p = \frac{\Delta I}{S v_h e_0}$$

Increase of leakage current due to illumination  $\Delta I$   
 drift time of holes through the detector  $v_h$

**$N_{eff}$  controlled by:**

- illumination intensity ( $p$ )
- operation voltage ( $p$ )
- temperature (trapping -detrapping process)

# Charge Injected Diode



*electron current pulse*

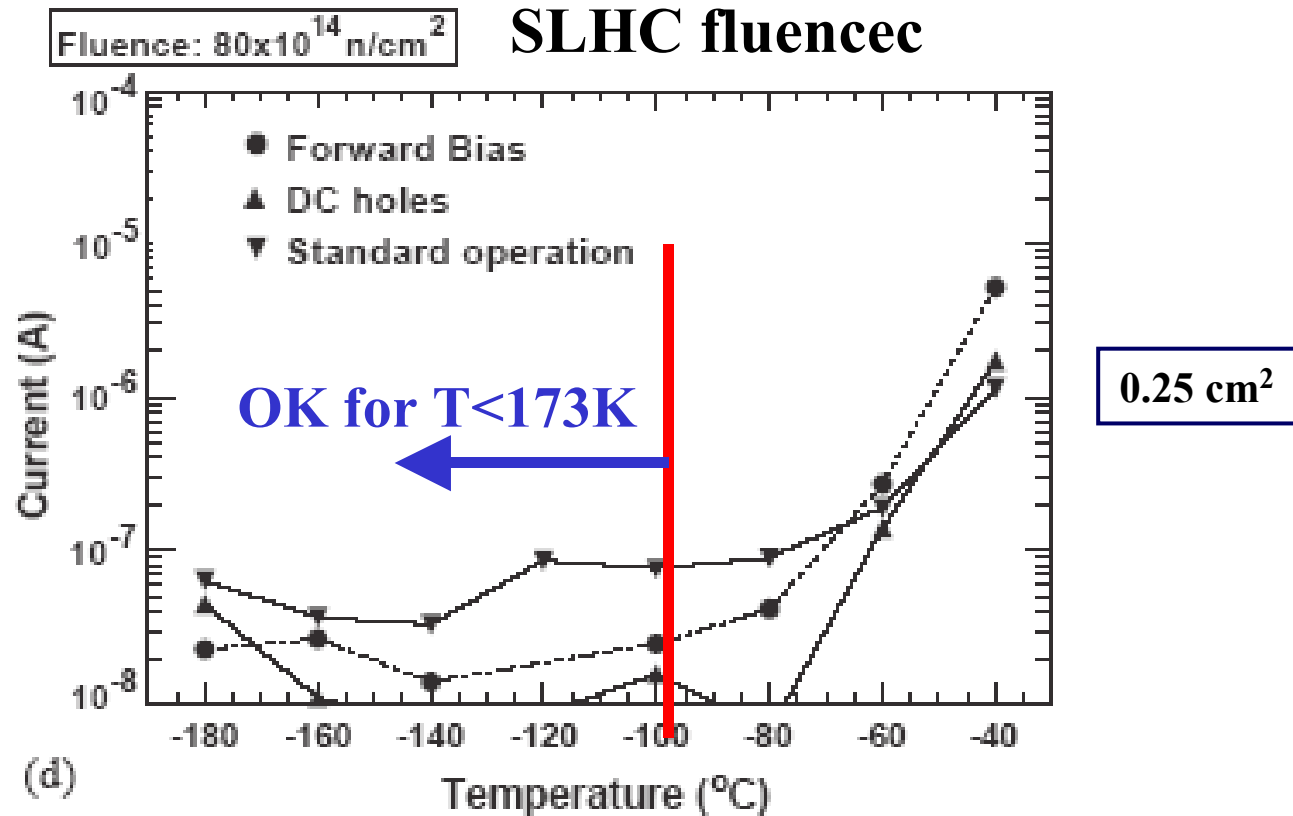
*hole current pulse*

$$\Phi_{eq} = 5 \times 10^{13} \text{ cm}^{-3} \text{ (after } \sim 10 \text{ days at } 20^\circ\text{C)}$$

**A significant reduction of  $V_{FD}$  in case of continuous hole injection!**

# CCE Measurements on CID

DC injection with a red laser (electrons or holes)  
Or current injection (forward bias)

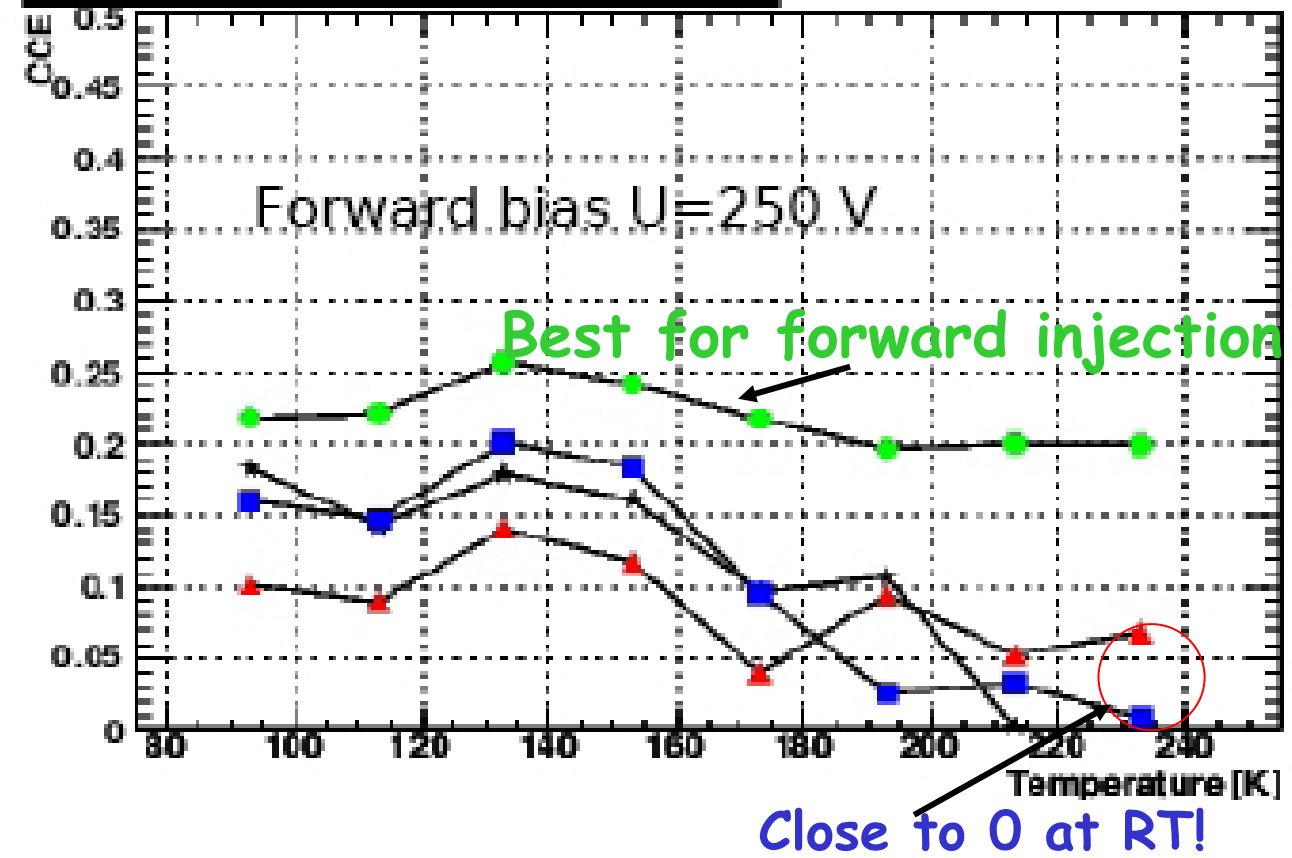




# CCE to $^{90}\text{Sr}$ source at various temperatures for CII



Sample w339xx,  $\Phi = 8 \times 10^{15}\text{ n/cm}^2$  SLHC fluence



## Summary

- o To increase CCE for SLHC, cryogenic operation of Si detectors at cryogenic temps may be necessary

Trapping can be frozen at such low temps

CID can stabilize the detector electric field and increase the detector CCE

CCE measurements on CID at cryogenic temperatures with laser and forward current injection have shown significant increase in CCE